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Preparation method for semiconductor structure, semiconductor structure and semiconductor memory

Abstract

A preparation method for a semiconductor structure includes the following operations. A bit line structure, active pillars, and a word line structure are formed in turn on a substrate. Bottom ends of the active pillars are connected to the bit line structure, and the active pillars are connected with the word line structure. A pillar-shaped conductive structure is formed on the active pillars, and a cup-shaped conductive structure is formed on the pillar-shaped conductive structure. There is an electrode gap between the pillar-shaped conductive structure and the cup-shaped conductive structure, and the pillar-shaped conductive structure and the cup-shaped conductive structure form a lower electrode. A dielectric layer is formed on a surface of the lower electrode. An upper electrode is formed on a surface of the dielectric layer. The upper electrode fills the electrode gap.

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Background/Summary

CROSS-REFERENCE TO RELATED APPLICATIONS (1) This is a continuation of International Application No. PCT/CN2021/110764 filed on Aug. 5, 2021, which claims priority to Chinese patent application No. 202110821150.9 filed on Jul. 20, 2021. The disclosures of these applications are hereby incorporated by reference in their entirety.

BACKGROUND

(1) A Dynamic Random-Access Memory (DRAM) is a semiconductor storage device commonly used in computers, and may be composed of many repeated storage cells. With the evolution of semiconductor technologies, the rapid development of an integrated circuit manufacturing process, and the trend of miniaturization of various electronic products, the size of the manufacturing process is continuously reduced, and the design of DRAM is developed towards high integration and high density, especially the height of a DRAM capacitor is developed towards the direction of a high depth-to-width ratio. At the same time, it is necessary to guarantee enough capacitor storage capacity per unit area.

SUMMARY

(2) Embodiments of the disclosure relate to, but are not limited to a preparation method for a semiconductor structure, the semiconductor structure and a semiconductor memory.

(3) In a first aspect, an embodiment of the disclosure provides a preparation method for a semiconductor structure, which includes the following operations.

(4) A substrate is provided.

(5) A bit line structure, a plurality of active pillars, and a word line structure are formed in turn on the substrate. Bottom ends of the active pillars are connected to the bit line structure, and the active pillars are connected with the word line structure.

(6) A pillar-shaped conductive structure is formed on the active pillars, and a cup-shaped conductive structure is formed on the pillar-shaped conductive structure. There is an electrode gap between the pillar-shaped conductive structure and the cup-shaped conductive structure, and the pillar-shaped conductive structure and the cup-shaped conductive structure form a lower electrode.

(7) A dielectric layer is formed on a surface of the lower electrode.

(8) An upper electrode is formed on a surface of the dielectric layer. The upper electrode fills the electrode gap.

(9) In a second aspect, an embodiment of the disclosure provides a semiconductor structure, and the semiconductor structure includes a substrate, a bit line structure, a plurality of active pillars, a word line structure, a pillar-shaped conductive structure, a cup-shaped conductive structure, a dielectric layer, and an upper electrode.

(10) The bit line structure, the active pillars and the word line structure are located above the substrate. Bottom ends of the active pillars are connected to the bit line structure, and the active pillars are connected with the word line structure.

(11) The pillar-shaped conductive structure is located above the active pillars.

(12) The cup-shaped conductive structure is located above the pillar-shaped conductive structure. The cup-shaped conductive structure and the pillar-shaped conductive structure form a lower electrode of the semiconductor structure.

(13) The dielectric layer is located on a surface of the lower electrode.

(14) The upper electrode covers a surface of the dielectric layer and fills an electrode gap.

(15) In a third aspect, an embodiment of the disclosure provides a semiconductor memory. The semiconductor memory includes a semiconductor structure. The semiconductor structure includes a substrate, a bit line structure, a plurality of active pillars, a word line structure, a pillar-shaped conductive structure, a cup-shaped conductive structure, a dielectric layer, and an upper electrode.

- (16) The bit line structure, the active pillars and the word line structure are located above the substrate. Bottom ends of the active pillars are connected to the bit line structure, and the active pillars are connected with the word line structure.
 - (17) The pillar-shaped conductive structure is located above the active pillars.
 - (18) The cup-shaped conductive structure is located above the pillar-shaped conductive structure. The cup-shaped conductive structure and the pillar-shaped conductive structure form a lower electrode of the semiconductor structure.
 - (19) The dielectric layer is located on a surface of the lower electrode.
 - (20) The upper electrode covers a surface of the dielectric layer and fills an electrode gap.
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Description

BRIEF DESCRIPTION OF THE DRAWINGS

- (1) FIG. 1 is a flow schematic diagram of a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (2) FIG. 2 is a first three-dimensional structure schematic diagram corresponding to a step S102 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (3) FIG. 3 is a second three-dimensional structure schematic diagram corresponding to a step S102 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (4) FIG. 4 is a third three-dimensional structure schematic diagram corresponding to a step S102 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (5) FIG. 5 is a fourth three-dimensional structure schematic diagram corresponding to a step S102 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (6) FIG. 6 is a fifth three-dimensional structure schematic diagram corresponding to a step S102 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (7) FIG. 7 is a sixth three-dimensional structure schematic diagram corresponding to a step S102 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (8) FIG. 8 is a seventh three-dimensional structure schematic diagram corresponding to a step S102 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (9) FIG. 9 is an eighth three-dimensional structure schematic diagram corresponding to a step S102 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (10) FIG. 10 is a first three-dimensional structure schematic diagrams corresponding to a step S103 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (11) FIG. 11 is a second three-dimensional structure schematic diagrams corresponding to a step S103 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (12) FIG. 12 is a third three-dimensional structure schematic diagrams corresponding to a step S103 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (13) FIG. 13 is a first schematic diagram of three-dimensional structure corresponding to a step S104 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.
- (14) FIG. 14 is a second schematic diagram of three-dimensional structure corresponding to a step S104 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.

disclosure.

(15) FIG. 15 is a third schematic diagram of three-dimensional structure corresponding to a step S104 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.

(16) FIG. 16A is a schematic diagram of three-dimensional structure corresponding to a step S105 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.

(17) FIG. 16B is a cross-sectional schematic diagram corresponding to a step S105 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.

(18) FIG. 17A is a schematic diagram of three-dimensional structure corresponding to a step S106 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.

(19) FIG. 17B is a cross-sectional schematic diagram corresponding to a step S106 in a preparation method for a semiconductor structure provided by an embodiment of the disclosure.

(20) FIG. 18 is a schematic diagram of composition structure of a semiconductor memory provided by an embodiment of the disclosure.

DETAILED DESCRIPTION

(21) Technical schemes in embodiments of the disclosure are clearly and completely described below in combination with drawings in the embodiments of the disclosure. It may be understood that the specific embodiments described here are only used to explain the disclosure, but not to limit the disclosure. In addition, it should be noted that, for ease of description, only the parts related to the disclosure are shown in the drawings.

(22) Unless otherwise defined, all technical and scientific terms used herein have the same meaning as commonly understood by those skilled in the technical field of the disclosure. Terminologies used herein are only for a purpose of describing the embodiments of the disclosure, and are not intended to limit the disclosure.

(23) In the following descriptions, “some embodiments” are involved, it describes a subset of all possible embodiments, but it may be understood that “some embodiments” may be the same subset or different subsets of all possible embodiments, and may be combined with each other in the case without conflicting.

(24) It should be pointed out that terms “first/second/third” involved in the embodiments of the disclosure only distinguish similar objects, and do not represent a specific order for the objects. Understandably, the “first/second/third” may interchange the specific sequence or precedence order in the case of permission, so that the embodiments of the disclosure described herein may be implemented in a sequence other than those illustrated or described herein.

(25) For a high depth-to-width ratio, in order to maintain the enough capacitor storage capacity, it may be difficult for a capacitor structure to maintain the enough stability.

(26) With the evolution of semiconductor technologies, the rapid development of an integrated circuit manufacturing process, and the trend of miniaturization of various electronic products, the size of the manufacturing process is continuously reduced, and the design of DRAM is developed towards high integration and high density. The height of a DRAM capacitor is developed towards the direction of a high depth-to-width ratio, and at the same time, it is necessary to guarantee enough capacitor storage capacity per unit area.

(27) However, in the case of the high depth-to-width ratio, it is difficult for a semiconductor structure to maintain the enough capacitor storage capacity while the enough stability is also maintained. A semiconductor structure provided by an embodiment of the disclosure may improve the storage capacity of a capacitor while the stability of the capacitor is guaranteed.

(28) The embodiments of the disclosure are described below in detail with reference to the drawings.

(29) In an embodiment of the disclosure, referring to FIG. 1, it shows a flow schematic diagram of

a preparation method for a semiconductor structure provided by the embodiment of the disclosure. As shown in FIG. 1, the method may include the following operations.

(30) At **S101**, a substrate is provided.

(31) The substrate may be a silicon substrate or other suitable substrate materials such as silicon, germanium, and silicon germanium compounds, and it is not specifically limited in the embodiment of the disclosure.

(32) At **S102**, a bit line structure, a plurality of active pillars and a word line structure are formed in turn on the substrate.

(33) Bottom ends of the active pillars are connected to the bit line structure, and the active pillars are connected with the word line structure.

(34) In some embodiments, the operation of forming a bit line structure, a plurality of active pillars, and a word line structure in turn on the substrate may include the following operations.

(35) The bit line structure is formed on the substrate, and the bit line structure extends along a first direction.

(36) The active pillars and the word line structure are formed on the bit line structure, and the word line structure extends along a second direction.

(37) In an embodiment, the operation of forming a bit line structure on the substrate may include the following operations.

(38) A first isolation structure and the bit line structure are formed above the substrate, and the first isolation structure and the bit line structure are located in the same plane.

(39) The first isolation structure is etched to form a bit line gap.

(40) A second isolation structure is formed above the bit line structure and the first isolation structure.

(41) Referring to FIG. 2, a substrate **10** is provided, and a first isolation structure **11** and a bit line structure **12** are formed above the substrate **10**. The first isolation structure **11** serves as a Shallow Trench Isolation (STI) structure of the semiconductor structure. The material of the first isolation structure includes one or more of suitable materials such as silicon dioxide and silicon nitride. The first isolation structure **11** may be formed in the mode of deposition formation.

(42) For example, a plurality of grooves arranged at intervals may be formed on the substrate **10**, and the first isolation structure **11** may be formed in the groove by deposition, so as to obtain the substrate including the first isolation structure, and then the bit line structure **12** is formed on the substrate between the first isolation structures **11**. In the embodiment of the disclosure, the bit line structure **12** is formed on a surface of the substrate between the first isolation structures **11**, and extends along the first direction, and the first isolation structure **11** and the bit line structure **12** are located in the same plane. For example, the bit line structure **12** may be formed by doping the semiconductor substrate **12** with one or more of suitable materials such as boron (B), phosphorus (P), arsenic (As), and germanium (Ge).

(43) In some embodiments, in order to avoid conduction between the bit line structure **12** and the substrate **10**, the method may further include the following operation. An insulating layer **15** is formed by deposition between the substrate **10** and the bit line structure **12**. The material of the insulating layer **15** may include one or more of suitable materials such as silicon dioxide. The bit line structure **12** and the first isolation structure **11** may be formed through the following steps. A semiconductor material layer, such as a monocrystalline silicon layer, is formed on the insulating layer **15** by an epitaxial method. Grooves distributed at intervals are formed on the semiconductor material layer, and the grooves are filled with an isolation material to form the first isolation structure **11**. The semiconductor material layer between the first isolation structures **11** is doped with one or more of suitable materials such as B, P, As and Ge to form the bit line structure **12**.

(44) Referring to FIG. 3, the first isolation structure **11** is etched to form an opening between the first isolation structures **11**, namely a bit line gap **13**. The bit line gap **13** is beneficial to reduction of the parasitic capacitance between bit lines.

(45) Referring to FIG. 4, a second isolation structure **14** is formed above the bit line structure **12** and the first isolation structure **11**, and the second isolation structure **14** may be formed in the mode of deposition formation, such as Low-Pressure Chemical Vapor Deposition (LPCVD). The material of the second isolation structure **14** may include one or more of suitable materials such as silicon dioxide (SiO_2) and silicon oxynitride (SiON).

(46) In an embodiment, the operation of forming a plurality of active pillars and a word line structure on the bit line structure may include the following operations.

(47) The second isolation structure is etched to form an active opening.

(48) Active pillars are formed at the active opening.

(49) A conductive layer is formed above the second isolation structure.

(50) The conductive layer is etched to form the word line gap and obtain the word line structure.

(51) A third isolation structure is formed above the word line structure.

(52) Referring to FIG. 5, the second isolation structure **14** is etched to form a plurality of active openings **16**. In the embodiment of the disclosure, the active openings **16** may be arranged in a mode of a square, a rectangle or other array arrangement, and this is not limited in the embodiment of the disclosure.

(53) The bit line structure **12** is located below source electrodes or drain electrodes of the active pillars in the same row, and the active pillars need to be connected with the bit line structure **12**. Therefore, the active opening **16** must guarantee that the bit line structure **12** is exposed. In the embodiment of the disclosure, the shape of the active opening **16** may be a circle or an ellipse.

(54) Referring to FIG. 6, the active pillar **17** is formed at the active opening **16**. In the embodiment of the disclosure, the active pillar **17** may be formed by the epitaxial method, and the material of the active pillar **17** may include monocrystalline silicon. Exemplarily, the height of the active pillar **17** may be higher than the height of the active opening **16**.

(55) Referring to FIG. 7, a conductive layer **18** is formed above the second isolation structure **14**, and the conductive layer **18** covers part of a surface of the active pillar **17**, and the conductive layer **18** is formed above the second isolation structure **14** to surround the active pillar **17**. The conductive layer **18** may be formed in a mode such as Physical Vapor Deposition (PVD), Chemical Vapor Deposition (CVD) or Atomic Layer Deposition (ALD), and the material of the conductive layer **18** may include one or more of suitable materials such as titanium nitride (TiN) and tungsten (W).

(56) In some embodiments, before forming a word line structure above the second isolation structure, the method may further include the following operation.

(57) A gate oxide layer is formed on a side surface of the active pillar.

(58) In the embodiment of the disclosure, before the conductive layer **18** is formed, the method may further include a step of forming the gate oxide layer (unshown in the figure) on the side surface of the active pillar **17**.

(59) For example, the second isolation structure **14** around the active pillar **17** is etched back through for example a dry etching method such as plasma etching, so as to expose a pillar side surface of the active pillar **17**, and the gate oxide layer is formed on the pillar side surface of the active pillar by modes such as thermal oxidation.

(60) In some embodiments, in a process of forming the gate oxide layer, the gate oxide layer is also formed on a top surface of the active pillar **17**, and the gate oxide layer on the top surface of the active pillar **17** needs to be removed, for example, removed by an etching method.

(61) Referring to FIG. 8, the conductive layer **18** is etched to form a word line gap **19** and obtain a word line structure **110**. The word line gap **19** is beneficial to reduction of interference between word lines.

(62) In the embodiment of the disclosure, the word line structure **110** extends along a second direction, and the second direction and the first direction are not parallel, namely extension directions of the bit line structure **12** and the word line structure **110** are not parallel. In FIG. 8, for

example, the first direction is perpendicular to the second direction.

(63) In some embodiments, while the conductive layer **18** is etched to form the word line gap **19**, the second isolation structure **14** may also be partially or completely etched in the same position, namely the length of the word line gap **19** in a perpendicular direction may be the same as the height of the conductive layer **18**, or may extend downwards to be longer than the height of the conductive layer **18**. In the semiconductor structure shown in FIG. **8**, the length of the word line gap is equal to the height of the conductive layer **18**.

(64) Referring to FIG. **9**, a third isolation structure **111** is formed above the word line structure **110**, and a top surface of the third isolation structure **111** and a top surface of the active pillar **17** are located in the same plane. The third isolation structure **111** may be formed by CVD, and the material of the third isolation structure **111** may include one or more of suitable materials such as silicon dioxide and silicon oxynitride. In other embodiments, the top surface of the third isolation structure **111** may also be lower or higher than the top surface of the active pillar **17**.

(65) At **S103**, a pillar-shaped conductive structure is formed on the active pillars.

(66) In the embodiment of the disclosure, the pillar-shaped conductive structure is formed on the active pillars.

(67) In an embodiment, the operation of forming a pillar-shaped conductive structure on the active pillars may include the following operations.

(68) A first support layer is formed above the active pillars.

(69) A first sacrifice layer is formed above the first support layer.

(70) A second support layer is formed above the first sacrifice layer.

(71) A first opening is formed in the second support layer, the first sacrifice layer and the first support layer. The first opening is opposite to the active pillars.

(72) A pillar-shaped conductive structure is formed in the first opening.

(73) Referring to FIG. **10**, the first support layer **112** is formed above the active pillars **17**, for example, the first support layer **112** is formed above the active pillars **17** and the third isolation structure **111**. The first sacrifice layer **113** is formed above the first support layer **112**. The first support layer **112** may be formed by methods such as PVD, CVD, or ALD, and the material of the first support layer **112** may include silicon nitride. The first sacrifice layer **113** may be formed by methods such as PVD, CVD, or ALD, and the material of the first sacrifice layer **113** may include silicon dioxide.

(74) Referring to FIG. **11**, the second support layer **114** is formed above the first sacrifice layer **113**, and the first opening **115** is formed in the second support layer **114**, the first sacrifice layer **113** and the first support layer **112**, and the first opening **115** is opposite to the active pillar **17**, so that the pillar-shaped conductive structure formed subsequently is connected with the active pillar **17**.

(75) The second support layer **114** may be formed by methods such as PVD, CVD, or ALD, and the material of the second support layer **114** may include silicon nitride. The first opening **115** may be formed by processes such as lithography and etching.

(76) Referring to FIG. **12**, the pillar-shaped conductive structure **116** is formed in the first opening **115**. The pillar-shaped conductive structure **116** may be formed by methods such as PVD, CVD, or ALD, and the material of the pillar-shaped conductive structure **116** may include one or more of suitable materials such as silicon nitride, tungsten, and titanium tungsten. Exemplarily, the pillar-shaped conductive structure **116** is completely formed in the first opening **115**.

(77) Before or after the pillar-shaped conductive structure **116** is formed (for example, while the first opening **115** is formed), the method may further include an operation of forming a plurality of first etchant inlets **117** in the second support layer **114**. For example, the second support layer **114** is etched to form the first etchant inlets **117** (only one first etchant inlet **117** is shown in FIG. **12** as an example), and the shape of the first etchant inlet **117** includes a circle, an ellipse, a triangle, a five-pointed star or a hexagon and the like. Here, only the circle is used as an example.

(78) In some embodiments, while the second support layer **114** is etched to form the first etchant

inlet **117**, the first sacrifice layer **113** may also be partially etched.

(79) At **S104**, a cup-shaped conductive structure is formed on the pillar-shaped conductive structure.

(80) In the embodiment of the disclosure, the cup-shaped conductive structure is formed on the pillar-shaped conductive structure, and there is an electrode gap between the pillar-shaped conductive structure and the cup-shaped conductive structure, and the pillar-shaped conductive structure and the cup-shaped conductive structure form a lower electrode.

(81) In an embodiment, the operation of forming the cup-shaped conductive structure on the pillar-shaped conductive structure may include the following operations.

(82) A second sacrifice layer is formed above the second support layer.

(83) A third support layer is formed above the second sacrifice layer.

(84) A second opening is formed in the third support layer and the second sacrifice layer.

(85) The cup-shaped conductive structure is formed in the second port.

(86) The second opening is opposite to the first opening, and the size of the second opening is greater than the size of the first opening. In other embodiments, the size of the second opening may also be less than or equal to the size of the first opening.

(87) Referring to FIG. **13**, the second sacrifice layer **118** is formed above the second support layer **114**, the third support layer **119** is formed above the second sacrifice layer **118**, and the second opening **120** is formed in the third support layer **119** and the second sacrifice layer **118**.

(88) The second sacrifice layer **118** may be formed by a process method such as PVD or CVD, and the material of the second sacrifice layer **118** may include silicon dioxide.

(89) The third support layer **119** may be formed by a process method such as PVD or CVD, and the material of the third support layer **119** may include silicon nitride. The second opening **120** may be formed by processes such as lithography and etching.

(90) The second opening **120** is opposite to the first opening **115**, namely opposite to the pillar-shaped conductive structure **116**, and exposes the pillar-shaped conductive structure **116**, so that the cup-shaped conductive structure may be connected with the pillar-shaped conductive structure **116** while the cup-shaped conductive structure is formed subsequently.

(91) In the embodiment of the disclosure, the lower electrode is formed by the cup-shaped conductive structure subsequently formed in the second opening **120** and the pillar-shaped conductive structure **116** together. While the second opening **120** is formed and the pillar-shaped conductive structure **116** is exposed, a part of the second support layer **114** may also be etched at the same time, and the second opening **120** further includes a partial opening formed by etching the second support layer **114**.

(92) Referring to FIG. **14**, the cup-shaped conductive structure **121** is formed in the second opening **120**. For example, the cup-shaped conductive structure **121** may be formed by methods such as PVD, CVD, or ALD, and the material of the cup-shaped conductive structure **121** may include conductive materials such as titanium nitride. The cup-shaped conductive structure **121** may be formed on the inner wall of the second opening **120**. In other embodiments, it may also be formed on the bottom wall of the second opening **120**. For example, the cup-shaped conductive structure **121** may also be formed on the top of the pillar-shaped conductive structure **116** exposed by the second opening **120**.

(93) In the embodiment of the disclosure, the lower electrode **122** is formed by the pillar-shaped conductive structure **116** and the cup-shaped conductive structure **121** together. A difference between the pillar-shaped conductive structure **116** and the cup-shaped conductive structure **121** is that the pillar-shaped conductive structure **116** fills the first opening **115** and is shaped like a pillar, and the cup-shaped conductive structure **121** is formed on the inner wall of the second opening **120** and is shaped like a cup. Moreover, the size of the second opening **120** is greater than the size of the first opening **116**, so that the size (diameter) of the cup-shaped conductive structure **121** is also greater than the size (diameter) of the pillar-shaped conductive structure **116**, through such a lower

electrode structure that “a cup is upper and a pillar is lower” and “the diameter of the cup is greater than the diameter of the pillar”, the stability of the structure is improved while the high depth-to-width ratio may be guaranteed.

(94) As shown in FIG. 14, in order to better represent the cup-shaped conductive structure 121, the inner wall thereof is marked as colorless, but it may be understood that the inner wall thereof includes a deposited conductive material.

(95) Before or after forming the cup-shaped conductive structure 121 (for example, while forming the second opening 120), the method may further include an operation of forming a plurality of second etchant inlets 123 in the third support layer 119. For example, the third support layer 119 is etched to form the second etchant inlets 123 (only one second etchant inlet 123 is shown in FIG. 14 as an example), and the shape of the second etchant inlet 123 includes a circle, an ellipse, a triangle, a five-pointed star or a hexagon and the like. Here, only the circle is used as an example.

(96) In some embodiments, while the third support layer 119 is etched to form the second etchant inlet 123, the second sacrifice layer 118 may also be partially etched.

(97) In some embodiments, after the cup-shaped conductive structure is formed in the second opening, the method may further include the following operations.

(98) A first etchant inlet and a second etchant inlet are formed in the second support layer and the third support layer respectively.

(99) The first etchant inlet and the second etchant inlet are used to remove the first sacrifice layer and the second sacrifice layer.

(100) Referring to FIG. 15, the second sacrifice layer 118 and the first sacrifice layer 113 may be removed by a mode of wet etching. An etchant is introduced through the second etchant inlet 123 and the first etchant inlet 117, and the two are in communication, so that the second sacrifice layer 118 and the first sacrifice layer 113 are etched and removed.

(101) For example, while the etchant is introduced through the second etchant inlet 123, part or the entire of the second sacrifice layer 118 is firstly etched and removed, and then the first etching inlet 117 is exposed, the etchant may enter the first sacrifice layer 113, and the first sacrifice layer 113 is removed.

(102) In the embodiment of the disclosure, the lower electrode 122 is formed by the pillar-shaped conductive structure 17 and the cup-shaped conductive structure 116 together.

(103) At S105, a dielectric layer is formed on a surface of the lower electrode.

(104) Referring to FIG. 16A, the formation of the dielectric layer 124 on the surface of the lower electrode 122 includes the following operations. The dielectric layer 124 is formed on an outer surface of the pillar-shaped conductive structure 17, and the dielectric layer 124 is formed on an inner surface and an outer surface of the cup-shaped conductive structure 121. The method of forming the dielectric layer 124 may include PVD, CVD, or ALD and the like. The material of the dielectric layer 124 may include high dielectric materials such as zirconium oxide (ZrO), hafnium oxide (HfO), and aluminum oxide (Al.sub.2O.sub.3).

(105) Referring to FIG. 16B, it shows a cross-section schematic diagram (front view direction) of a structure obtained in this step.

(106) At S106, an upper electrode is formed on a surface of the dielectric layer.

(107) For example, the upper electrode fills the electrode gap.

(108) Referring to FIG. 17A, the upper electrode 125 is formed on the surface of the dielectric layer, and the upper electrode 125 fills the electrode gap. The electrode gap may include a gap formed after etching the first sacrifice layer 113 and the second sacrifice layer 118, and a gap inside the cup-shaped conductive structure 121, and not include the bit line gap 13 and the word line gap 19. The method of forming the upper electrode 125 may be PVD, CVD, or ALD and the like, and the material of the upper electrode 125 may include polysilicon, silicon germanium, or titanium nitride and the like.

(109) Referring to FIG. 17B, it shows a cross-section schematic diagram (front view direction) of a

structure obtained in this step.

(110) In some embodiments, after a cup-shaped conductive structure is formed on the pillar-shaped conductive structure, the method may further include the following operation.

(111) The steps of forming the pillar-shaped conductive structure and forming the cup-shaped conductive structure on the pillar-shaped conductive structure are cyclically performed above the cup-shaped conductive structure, until the number of the cup-shaped structures reaches a preset number, as to form the lower electrode.

(112) It should be noted that, in the embodiment of the disclosure, the step of forming the pillar-shaped conductive structure and the cup-shaped conductive structure may be repeated, until the number of the cup-shaped conductive structures reaches the preset number, thereby the lower electrode including a plurality of layers of “pillar-shaped conductive structure—cup-shaped conductive structure” is obtained.

(113) In addition, in the embodiments of the disclosure, “formation”, “deposition”, “etching” and the like may be formed by any processes suitable for existing materials.

(114) In the preparation method for the semiconductor structure provided by the embodiment of the disclosure, the lower electrode structure of which the bottom is pillar-shaped and the upper is cup-shaped is formed to obtain the semiconductor structure with the stable structure. In addition, the distance between the word line and the bit line is relatively small, and the embodiment of the disclosure reduces the mutual interference between word lines, between bit lines and between the bit line and the word line through the word line gap and the bit line gap. In the semiconductor structure obtained by the preparation method of the embodiment of the disclosure, the lower part of the lower electrode is a pillar structure (pillar-shaped conductive structure), the upper part of the lower electrode is a cup structure (cup-shaped conductive structure), and the diameter of the pillar structure is less than the diameter of the cup structure, so that the semiconductor structure is more stable. In the embodiment of the disclosure, a manufacturing process of the pillar structure and the cup structure may also be repeated to form a stacked structure with more than two layers (the two layers refer to one layer of the pillar structure and one layer of the cup structure). In addition, since gaps are formed between the word lines and the bit lines, the preparation method of the embodiment of the disclosure may also reduce read and write interference.

(115) This embodiment provides a preparation method for a semiconductor structure. A substrate is provided. A bit line structure, a plurality of active pillars, and a word line structure are formed in turn on the substrate. Bottom ends of the active pillars are connected to the bit line structure, and the active pillars are connected with the word line structure. A pillar-shaped conductive structure is formed on the active pillar, and a cup-shaped conductive structure is formed on the pillar-shaped conductive structure. There is an electrode gap between the pillar-shaped conductive structure and the cup-shaped conductive structure, and a lower electrode is formed by the pillar-shaped conductive structure and the cup-shaped conductive structure together. A dielectric layer is formed on a surface of the lower electrode. An upper electrode is formed on a surface of the dielectric layer, and the upper electrode fills the electrode gap. In this way, by forming the lower electrode of which the lower part is the pillar-shaped conductive structure and the upper part is the cup-shaped conductive structure, the storage capacity of the capacitor is increased while the stability of the semiconductor structure is also improved.

(116) In another embodiment of the disclosure, FIG. 17A shows a three-dimensional structure schematic diagram of a semiconductor structure provided by an embodiment of the disclosure, and FIG. 17B shows a cross-section schematic diagram of a semiconductor structure provided by an embodiment of the disclosure. As shown in FIG. 17A and FIG. 17B, the semiconductor structure may include a substrate **10**, a bit line structure **12**, a plurality of active pillars **17**, a word line structure **110**, a pillar-shaped conductive structure, a cup-shaped conductive structure, a dielectric layer **124**, and an upper electrode **125**.

(117) The bit line structure **12**, the active pillars **17** and the word line structure **110** are located

above the substrate **10**. Bottom ends of the active pillars **17** are connected to the bit line structure **12**, and the active pillars **17** are connected with the word line structure **110**.

(118) The pillar-shaped conductive structure is located above the active pillars **17**.

(119) The cup-shaped conductive structure is located above the pillar-shaped conductive structure. A lower electrode **122** of the semiconductor structure is formed by the cup-shaped conductive structure and the pillar-shaped conductive structure together.

(120) The dielectric layer **124** is located on a surface of the lower electrode **122**.

(121) The upper electrode **125** covers a surface of the dielectric layer **124** and fills an electrode gap.

(122) In some embodiments, the bit line structure **12** is located on the substrate **10**, and the bit line structure **12** extends along a first direction.

(123) The active pillars **17** and the word line structure **110** are located on the bit line structure **12**, and the word line structure **110** extends along a second direction.

(124) In some embodiments, the semiconductor structure may further include a first isolation structure **11** and a bit line gap **13** located in the first isolation structure. The first isolation structure **11** and the bit line structure **12** are formed in the same plane.

(125) In some embodiments, the semiconductor structure may further include an insulating layer **15** between the bit line structure **12** and the substrate **10**.

(126) In some embodiments, the semiconductor structure may further include a second isolation structure **14**, and the second isolation structure **14** is located above the bit line structure **12** and the first isolation structure **11**. The word line structure **110** is located above the second isolation structure **14**, and there is a word line gap **19** between word line structures **110**.

(127) In some embodiments, the semiconductor structure may further include a third isolation structure **111**. The third isolation structure **111** is located above the word line structure **110**, and a top surface of the third isolation structure **111** and a top surface of the active pillar **17** are located in the same plane.

(128) In some embodiments, the semiconductor structure may further include a gate oxide layer (unshown in the figure). The gate oxide layer covers a pillar side surface of the active pillar **17**.

(129) In some embodiments, the semiconductor structure may further include a first support layer **112** located on the active pillar **17**, a second support layer **114** located on the top of the pillar-shaped conductive structure, and a third support layer located on the top of the cup-shaped conductive structure **119**.

(130) In some embodiments, the size of a cross section, perpendicular to the extension direction thereof, of the cup-shaped conductive structure is greater than the size of a cross section, perpendicular to the extension direction thereof, of the pillar-shaped conductive structure.

(131) In some embodiments, the semiconductor structure may further include a plurality of groups of the stacked pillar-shaped conductive structures and cup-shaped conductive structures.

(132) This embodiment provides a semiconductor structure, and the semiconductor structure includes a substrate, a bit line structure, a plurality of active pillars, a word line structure, a pillar-shaped conductive structure, a cup-shaped conductive structure, a dielectric layer, and an upper electrode. The bit line structure, the active pillars and the word line structure are located above the substrate. Bottom ends of the active pillars are connected to the bit line structure, and the active pillars are connected with the word line structure. The pillar-shaped conductive structure is located above the active pillars. The cup-shaped conductive structure is located above the pillar-shaped conductive structure. The semiconductor structure is formed by the cup-shaped conductive structure and the pillar-shaped conductive structure form a lower electrode. The dielectric layer is located on a surface of the lower electrode. The upper electrode covers a surface of the dielectric layer and fills an electrode gap. In this way, since the lower part of the lower electrode of the semiconductor structure is the pillar-shaped conductive structure, and the upper part is the cup-shaped conductive structure, the storage capacity of the capacitor is increased while it also makes the semiconductor structure more stable. In addition, because the size of the cross section,

perpendicular to the extension direction thereof, of the cup-shaped conductive structure is greater than the size of the cross section, perpendicular to the extension direction thereof, of the pillar-shaped conductive structure, the stability of the semiconductor structure is further improved. Moreover, since the gap is formed between the word line structure and the bit line structure, the read and write interference may also be reduced. At the same time, the plurality of groups of the stacked pillar-shaped conductive structures and cup-shaped conductive structures may also be formed, the stability of the semiconductor structure is guaranteed while the depth-to-width ratio of the semiconductor structure is increased.

(133) In another embodiment of the disclosure, referring to FIG. 18, it shows a composition structure schematic diagram of a semiconductor memory provided by an embodiment of the disclosure. As shown in FIG. 18, the semiconductor memory 20 may include the semiconductor structure in any one of the previous embodiments.

(134) In some embodiments, the semiconductor memory 20 may be a DRAM.

(135) Further, in a specific example, the semiconductor structure may be a capacitor structure, and may also be referred to as a DRAM capacitor structure. In this way, for the semiconductor memory 20, based on the semiconductor structure described in any one of the previous embodiments, the semiconductor memory 20 may increase the storage capacity of the capacitor while also improving the stability of the capacitor structure.

(136) It should be noted that in the disclosure, terms “include”, “contain” or any other variants thereof are intended to cover non-exclusive inclusion, so that a process, a method, an article or a device including a series of elements not only includes those elements, but also includes other elements that are not explicitly listed, or elements inherent to the process, the method, the article, or the device. In the case without more restrictions, an element defined by a sentence “including a . . . ” does not exclude the existence of other same elements in the process, the method, the article, or the device that includes the element.

(137) The serial numbers of the above embodiments of the disclosure are only for descriptions, and do not represent the superiority or inferiority of the embodiments.

(138) The methods disclosed in the several method embodiments provided in the disclosure may be combined arbitrarily in the case without conflicting, as to obtain a new method embodiment.

(139) The features disclosed in the several product embodiments provided in the disclosure may be combined arbitrarily in the case without conflicting, as to obtain a new product embodiment.

(140) The features disclosed in the several method or device embodiments provided in the disclosure may be combined arbitrarily in the case without conflicting, as to obtain a new method embodiment or device embodiment.

Claims

1. A semiconductor structure, comprising: a substrate; a bit line structure, a plurality of active pillars, and a word line structure located above the substrate; wherein bottom ends of the active pillars are connected to the bit line structure, and the active pillars are connected with the word line structure; a pillar-shaped conductive structure, located above each active pillar of the active pillars; a cup-shaped conductive structure, located above the pillar-shaped conductive structure; wherein the cup-shaped conductive structure and the pillar-shaped conductive structure form a lower electrode of the semiconductor structure; a dielectric layer, located on a surface of the lower electrode; and an upper electrode, covering a surface of the dielectric layer and filling an electrode gap between adjacent pillar-shaped conductive structure and between adjacent cup-shaped conductive structure, wherein the upper electrode is opposite to an outer surface of the pillar-shaped conductive structure and an inner surface and an outer surface of the cup-shaped conductive structure, so as to form a capacitor structure.

2. The semiconductor structure of claim 1, wherein: the bit line structure is located on the substrate,

and the bit line structure extends along a first direction; the active pillars and the word line structure are located on the bit line structure, and the word line structure extends along a second direction.

3. The semiconductor structure of claim 2, further comprising a first isolation structure and a bit line gap located in the first isolation structure; wherein the first isolation structure and the bit line structure are formed in a same plane.

4. The semiconductor structure of claim 3, further comprising a second isolation structure, and the second isolation structure is located above the bit line structure and the first isolation structure; wherein the word line structure is located above the second isolation structure, and there is a word line gap between word line structures.

5. The semiconductor structure of claim 4, further comprising a third isolation structure; wherein the third isolation structure is located above the word line structure, and a top surface of the third isolation structure and a top surface of the active pillars are located in a same plane.

6. The semiconductor structure of claim 5, further comprising a gate oxide layer; wherein the gate oxide layer covers a pillar side surface of the active pillars.

7. The semiconductor structure of claim 1, further comprising: a first support layer located on the active pillars, a second support layer located on top of the pillar-shaped conductive structure, and a third support layer located on top of the cup-shaped conductive structure.

8. The semiconductor structure of claim 7, wherein a size of a cross section of the cup-shaped conductive structure perpendicular to the extension direction of the cup-shaped conductive structure is greater than a size of a cross section of the pillar-shaped conductive structure perpendicular to the extension direction of the pillar-shaped conductive structure.

9. The semiconductor structure of claim 1, further comprising a plurality of groups of the pillar-shaped conductive structure and cup-shaped conductive structure which are stacked.

10. A semiconductor memory, comprising a semiconductor structure, wherein the semiconductor structure comprises: a substrate; a bit line structure, a plurality of active pillars, and a word line structure located above the substrate; wherein bottom ends of the active pillars are connected to the bit line structure, and the active pillars are connected with the word line structure; a pillar-shaped conductive structure, located above each active pillar of the active pillars; a cup-shaped conductive structure, located above the pillar-shaped conductive structure; wherein the cup-shaped conductive structure and the pillar-shaped conductive structure form a lower electrode of the semiconductor structure; a dielectric layer, located on a surface of the lower electrode; and an upper electrode, covering a surface of the dielectric layer and filling an electrode gap between adjacent pillar-shaped conductive structure and between adjacent cup-shaped conductive structure, wherein the upper electrode is opposite to an outer surface of the pillar-shaped conductive structure and an inner surface and an outer surface of the cup-shaped conductive structure, so as to form a capacitor structure.
